



**scia Clean 800**

**HIGH QUALITY CLEANING AND QUALIFICATION**

## Features & Benefits

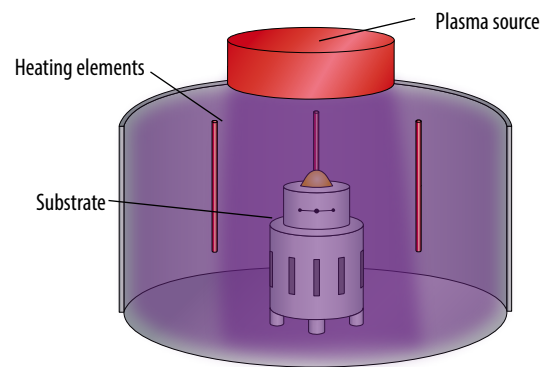
- Low base pressure and fast pumping due to electro-polished and heated vacuum chamber
- Separate substrate heating for improved desorption
- Qualification of residual contamination by high sensitive mass spectroscopy
- Optional plasma source for advanced cleaning with H<sub>2</sub> plasma
- Recipes for repeatable temperature ramps and fully automated cleaning cycles
- Crane for loading of large and heavy substrates

## Applications

- Ultra high purity cleaning of X-ray optics
- Cleaning of components for beam line accelerators
- Outgassing qualification of complex vacuum assemblies

## Principle

- Dry Cleaning
  - Removing of contamination from the 3-dimensional shaped substrates by using ultra high vacuum (vacuum desorption)
  - Further cleaning progress with optional heating of the substrate and/or chamber (thermal desorption) and applying plasma treatment



## Technical Data

<b>Substrate size (up to)</b>	800 mm dia., 500 mm height, 500 kg
<b>Substrate heating</b>	Radiation heaters (4.5 kW) up to 250 °C
<b>Chamber heating and cooling</b>	Pressurized water based heating up to 150 °C and cooling (8 kW)
<b>Plasma sources</b>	Optional ICP plasma source (PI400), max. 2.5 kW
<b>Base pressure</b>	< 5 x 10 <sup>-9</sup> mbar
<b>Quality control</b>	Mass spectrometer for quantitative outgassing measurement
<b>System dimension (W x D x H)</b>	1.30 m x 2.50 x 1.40 m (without electrical rack and pumps)
<b>Configuration</b>	Single chamber with top lid, optional crane for loading of heavy substrates
<b>Software interfaces</b>	SECS II / GEM, OPC

